



## Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-06-25
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	Antonella Lanzafame	Representative title	AMSMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty statement**

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**Legal statement**

Supplier acceptance*	Legal declaration*	Standard
true		

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
ST87M01-1111	115P*HR00BE2	A	AF1A	2024-06-25
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	660	mg	Each	ECOPACK® 3
Identity	Authority			
Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	245	3		
Bulk solder termination	Terminal plating	Terminal base alloy		Comment
Not Applicable	Tin (Sn), immersion	Copper Alloy		0

Package designator	Package size	Number of instances	Shape	
mounted board	12.8 x 10.6	43	nac	
Comment				
Comment	BOFX SMD MODULE			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020	Response
1 - Product(s) meets EU ELV requirements without any exemptions	true
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Exemption Id.	Description

QueryList : California Prop65 list, dated 17th Nov 2023	Response		
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen	FALSE		
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen	TRUE		
Substance	amount in product (mg)	Application	ppm in product
Nickel	7.672	alloy	11624

QueryList :Customer	Response
QUERY	Response

QueryList : Chinese RoHS , references : SJT 11364 – 2014 and GBT 26572 – 2014	Response			
QUERY	Response			
1 - Product(s) requires marking for the presence of restricted substances and must be marked with an Environmental Protection Use Period under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
2 - Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products	false			
Hazardous substance				
Lead (Pb)	Cadmium (Cd)	Mercury (Hg)	Hexavalent Chromium (Cr VI)	PBB & PBDE
O	O	O	O	O

QueryList : REACH-23rd January 2024	Response			
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH	false			
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Diboron trioxide	1000 ppm	0.16	on glass	1989
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH	false			
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material
Diboron trioxide	1000 ppm	0.15943	on glass	1989



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	<b>Cobalt, Gold, Tantalum, Tin, Tungsten,</b>

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	false

Stockholm Convention Persistent Organic Pollutants	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	true

QueryList : EUSRR Directive	Response
Product contains hazardous materials listed in EUSRR Annex II	TRUE

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene, Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	115P*HR00BE2		660.0000		11296447.0	497796.0
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
U204 (STNB81195CBBFMT0)	M-011 Other inorganic materials	12.836	mg	supplier	die	Silicon(Si)	7440-21-3		1.877	mg	146229	2844
U204 (STNB81195CBBFMT0)				supplier	metallisation	Aluminium(Al)	7429-90-5		0.011	mg	857	17
U204 (STNB81195CBBFMT0)				supplier	metallisation	Copper(Cu)	7440-50-8		0.054	mg	4207	82
U204 (STNB81195CBBFMT0)				supplier	metallisation	Cobalt(Co)	7440-48-4		0.001	mg	78	2
U204 (STNB81195CBBFMT0)				supplier	metallisation	Titanium(Ti)	7440-32-6		0.006	mg	467	9
U204 (STNB81195CBBFMT0)				supplier	metallisation	Tungsten(W)	7440-33-7		0.006	mg	467	9
U204 (STNB81195CBBFMT0)				supplier	Passivation	Silicon Nitride (SiN)	12033-89-5		0.006	mg	467	9
U204 (STNB81195CBBFMT0)				supplier	passivation	Silicon Oxide	7631-86-9		0.068	mg	5298	103
U204 (STNB81195CBBFMT0)				Supplier	laminate	Glass, oxide	65997-17-3		1.267	mg	98707	1920
U204 (STNB81195CBBFMT0)				Supplier	laminate	Silicon dioxide	7631-86-9		0.631	mg	49159	956
U204 (STNB81195CBBFMT0)				Supplier	laminate	Bismaleimide-Triazine resin	Proprietary		0.309	mg	24073	468
U204 (STNB81195CBBFMT0)				Supplier	laminate	Epoxy resin	Proprietary		0.215	mg	16750	326
U204 (STNB81195CBBFMT0)				Supplier	laminate	Other substances	Proprietary		0.166	mg	12932	252
U204 (STNB81195CBBFMT0)				Supplier	laminate	Cured Resin	Proprietary		0.186	mg	14490	282
U204 (STNB81195CBBFMT0)				Supplier	laminate	Colorant	147-14-8		0.001	mg	78	2
U204 (STNB81195CBBFMT0)				Supplier	laminate	Organic pigment	Proprietary		0.001	mg	78	2
U204 (STNB81195CBBFMT0)				Supplier	laminate	Barium sulfate	7727-43-7		0.029	mg	2259	44
U204 (STNB81195CBBFMT0)				Supplier	laminate	Talc	14807-96-6		0.037	mg	2883	56
U204 (STNB81195CBBFMT0)				Supplier	laminate	Aluminium hydroxide	21645-51-2		0.001	mg	78	2
U204 (STNB81195CBBFMT0)				Supplier	laminate	Antifoamer and Leveling agent	Proprietary		0.013	mg	1013	20
U204 (STNB81195CBBFMT0)				Supplier	laminate	Copper	7440-50-8		2.453	mg	19103	3717
U204 (STNB81195CBBFMT0)				Supplier	laminate	Nickel	7440-02-0		0.154	mg	11998	233
U204 (STNB81195CBBFMT0)				Supplier	laminate	Gold	7440-57-5		0.033	mg	2571	50
U204 (STNB81195CBBFMT0)				Supplier	Mold Compound	Epoxy Resin A	Proprietary		0.373	mg	29059	565
U204 (STNB81195CBBFMT0)				Supplier	Mold Compound	Epoxy Resin B	Proprietary		0.124	mg	9660	188
U204 (STNB81195CBBFMT0)				Supplier	Mold Compound	Phenol Resin A	Proprietary		0.124	mg	9660	188
U204 (STNB81195CBBFMT0)				Supplier	Mold Compound	Silica, vitreous	60676-86-0		3.232	mg	251792	4897
U204 (STNB81195CBBFMT0)				Supplier	Mold Compound	Silicon dioxide	7631-86-9		0.994	mg	77438	1506
U204 (STNB81195CBBFMT0)				Supplier	Mold Compound	Metal Hydroxide	Proprietary		0.099	mg	7713	150
U204 (STNB81195CBBFMT0)				Supplier	Mold Compound	Carbon Black	1333-86-4		0.025	mg	1948	38
U204 (STNB81195CBBFMT0)				Supplier	Cu pillar	Copper	7440-50-8		0.105	mg	8180	159
U204 (STNB81195CBBFMT0)				Supplier	Cu pillar	Tin	7440-31-5		0.055	mg	4285	83
U204 (STNB81195CBBFMT0)				Supplier	Cu pillar	Silver	7440-22-4		0.001	mg	78	2
U204 (STNB81195CBBFMT0)				Supplier	Cu pillar	Copper	7440-50-8		0.116	mg	9037	176
U204 (STNB81195CBBFMT0)				Supplier	Cu pillar	Tin	7440-31-5		0.062	mg	4830	94
U204 (STNB81195CBBFMT0)				Supplier	Cu pillar	Silver	7440-22-4		0.001	mg	78	2
U203 (8Y38472018)	M-011 Other inorganic materials	6.790	mg	supplier	Crystal blank	SiO2	7440-21-3		0.527	mg	77590	798
U203 (8Y38472018)				supplier	Electrode	Cr	7440-47-3		0.056	mg	8190	84
U203 (8Y38472018)				supplier	Electrode	Gold (Au)	7440-57-5		0.003	mg	431	4
U203 (8Y38472018)				supplier	Base	Aluminum Oxide	1344-28-1		3.849	mg	566881	5832
U203 (8Y38472018)				supplier	Base	SiO2	7631-86-9		0.171	mg	25215	259
U203 (8Y38472018)				supplier	Base	Cr2O3	1308-38-9		0.043	mg	6289	65
U203 (8Y38472018)				supplier	Base	Molybdenum	7439-98-7		0.043	mg	6289	65
U203 (8Y38472018)				supplier	kovar ring	Iron (Fe)	7439-89-6		0.050	mg	7337	75
U203 (8Y38472018)				supplier	kovar ring	Nickel (Ni)	7440-02-0		0.027	mg	4015	41
U203 (8Y38472018)				supplier	kovar ring	Cobalt (Co)	7440-48-4		0.017	mg	2492	26
U203 (8Y38472018)				supplier	plate	Gold	7440-50-8		0.027	mg	3945	41
U203 (8Y38472018)				supplier	plate	Nickel (Ni)	7440-02-0		0.114	mg	16820	173
U203 (8Y38472018)				supplier	Metallizing	W	7440-33-7		0.047	mg	6922	71
U203 (8Y38472018)				supplier	Solder	Ag	7440-22-4		0.100	mg	14743	152
U203 (8Y38472018)				supplier	Solder	Cu	7440-50-8		0.041	mg	6022	62
U203 (8Y38472018)				supplier	Base Material	Fe	7439-89-6		0.770	mg	113364	1166
U203 (8Y38472018)				supplier	Base Material	Ni	7440-02-0		0.420	mg	61919	637
U203 (8Y38472018)				supplier	Base Material	Co	7440-48-4		0.245	mg	36093	371
U203 (8Y38472018)				supplier	Base Material	Mn	7439-96-5		0.006	mg	915	9
U203 (8Y38472018)				supplier	Base Material	C	7440-44-0		0.000	mg	21	0
U203 (8Y38472018)				supplier	Base Material	Si	7440-21-3		0.001	mg	149	2
U203 (8Y38472018)				supplier	Base Material	Cr	7440-47-3		0.001	mg	100	1
U203 (8Y38472018)				supplier	Base Material	Ni	7440-02-0		0.133	mg	19535	201



U203 (8Y38472018)				supplier	Silver adhesive	Ag	7440-22-4		0.070	mg	10309	106
U203 (8Y38472018)				supplier	Silver adhesive	SiO2	631-86-9		0.005	mg	736	8
U203 (8Y38472018)				supplier	Silver adhesive	Silicone resin	Proprietary		0.025	mg	3682	38
U201 (ST8700)	M-011 Other inorganic materials	20.534	mg	supplier	Silicon	Silicon	7440-21-3		12.865	mg	626530	19493
U201 (ST8700)				supplier	Coating film	Silica	Proprietary		0.430	mg	20929	651
U201 (ST8700)				supplier	Coating film	Epoxy resin	Proprietary		0.159	mg	7766	242
U201 (ST8700)				supplier	Coating film	Acrylic resin	Proprietary		0.159	mg	7766	242
U201 (ST8700)				supplier	Solder ball	Tin	7440-31-5		4.005	mg	195056	6069
U201 (ST8700)				supplier	Solder ball	Silver	7440-22-4		0.168	mg	8170	254
U201 (ST8700)				supplier	Solder ball	Copper	7440-50-8		0.021	mg	1021	32
U201 (ST8700)				supplier	Repassivation polymer(LTC9320)	Gamma-Butyrolactone	96-48-0		0.150	mg	7307	227
U201 (ST8700)				supplier	Repassivation polymer(LTC9320)	Polyamic acid ester	Proprietary		0.117	mg	5683	177
U201 (ST8700)				supplier	Repassivation polymer(LTC9320)	Dimethyl sulfoxide	67-68-5		0.043	mg	2111	66
U201 (ST8700)				supplier	Repassivation polymer(LTC9320)	Tetraethylene glycol dimethacrylate	Proprietary		0.017	mg	812	25
U201 (ST8700)				supplier	Repassivation polymer(LTC9320)	Trialkoxylated amidocarbonylic silane	Proprietary		0.003	mg	162	5
U201 (ST8700)				supplier	Repassivation polymer(LTC9320)	Oxime derivative	Proprietary		0.003	mg	162	5
U201 (ST8700)				supplier	Runner/UBM (Metal Sputter)	Titanium	7440-32-6		0.008	mg	400	12
U201 (ST8700)				supplier	Runner/UBM (Metal Sputter)	Copper	7440-50-8		0.032	mg	1574	49
U201 (ST8700)				supplier	Runner/UBM (Metal Sputter)	Titanium	7440-32-6		0.008	mg	400	12
U201 (ST8700)				supplier	Runner/UBM (Metal Sputter)	Copper	7440-50-8		0.032	mg	1574	49
U201 (ST8700)				supplier	RDL Copper	Copper	7440-50-8		0.970	mg	47234	1470
U201 (ST8700)				supplier	UBM Copper	Copper	7440-50-8		1.342	mg	65341	2033
U100 (ST4Si2M0022TPSL9)		6.943	mg	supplier	die	Silicon (Si)	7440-21-3		5.543	mg	798413	8398
U100 (ST4Si2M0022TPSL9)				supplier	metallization	Aluminium (Al)	7429-90-5		0.023	mg	3313	35
U100 (ST4Si2M0022TPSL9)				supplier	metallization	Copper (Cu)	7440-50-8		0.079	mg	11379	120
U100 (ST4Si2M0022TPSL9)				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	144	2
U100 (ST4Si2M0022TPSL9)				supplier	metallization	Tantalum (Ta)	7440-25-7		0.028	mg	4033	42
U100 (ST4Si2M0022TPSL9)				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	144	2
U100 (ST4Si2M0022TPSL9)				supplier	Passivation	Silicon Nitride	12033-89-5		0.015	mg	2161	23
U100 (ST4Si2M0022TPSL9)				supplier	Passivation	Silicon Oxide	7631-86-9		0.051	mg	7346	77
U100 (ST4Si2M0022TPSL9)				supplier	resists	PIX1 Polyimide	96-48-0		0.062	mg	8877	93
U100 (ST4Si2M0022TPSL9)				supplier	resists	Polyamide	Proprietary		0.043	mg	6214	65
U100 (ST4Si2M0022TPSL9)				supplier	resists	2-Methoxy-1-methylethyl acetate	108-65-6		0.007	mg	977	10
U100 (ST4Si2M0022TPSL9)				supplier	resists	Organosilane Compounds	Proprietary		0.004	mg	533	6
U100 (ST4Si2M0022TPSL9)				supplier	resists	Photoinitiator	Proprietary		0.007	mg	977	10
U100 (ST4Si2M0022TPSL9)				supplier	resists	Proprietary Ingredients	Proprietary		0.007	mg	977	10
U100 (ST4Si2M0022TPSL9)				supplier	Metal	Titanium	7440-32-6		0.001	mg	79	1
U100 (ST4Si2M0022TPSL9)				supplier	metal	Copper	7440-50-8		0.007	mg	940	10
U100 (ST4Si2M0022TPSL9)				supplier	plating materials	Copper	7440-50-8		0.107	mg	15469	163
U100 (ST4Si2M0022TPSL9)				supplier	solder ball	Tin (Sn)	7440-31-5		0.651	mg	93736	986
U100 (ST4Si2M0022TPSL9)				supplier	solder ball	Copper (Cu)	7440-50-8		0.003	mg	477	5
U100 (ST4Si2M0022TPSL9)				supplier	solder ball	Silver (Ag)	7440-22-4		0.008	mg	1145	12
U100 (ST4Si2M0022TPSL9)				supplier	solder ball	Nickel (Ni)	7440-02-0		0.000	mg	48	1
U100 (ST4Si2M0022TPSL9)				supplier	plastic/polymers	Polyethylene terephthalate	25038-59-9		0.205	mg	29539	311
U100 (ST4Si2M0022TPSL9)				supplier	plastic/polymers	Silica	Proprietary		0.051	mg	7385	78
U100 (ST4Si2M0022TPSL9)				supplier	plastic/polymers	Epoxy resin	Proprietary		0.019	mg	2743	29
U100 (ST4Si2M0022TPSL9)				supplier	plastic/polymers	Acrylic resin	Proprietary		0.019	mg	2743	29
U100 (ST4Si2M0022TPSL9)				supplier	plastic/polymers	Carbon Black	1333-86-4		0.001	mg	211	2
PCB		280.300	mg	supplier	PWB Base Material_copper foil	Copper (Cu)	7440-50-8		82.000	mg	292544	124242
PCB				supplier	PWB Base Material_laminate	Epoxy resin	26265-08-7		79.000	mg	281841	119697
PCB				supplier	PWB Base Material_laminate	Fiber glass	65997-17-3		89.000	mg	317517	134848
PCB				supplier	PWB Solder Resist	Barium Sulfate	7727-43-7		12.000	mg	42811	18182
PCB				supplier	PWB Solder Resist	Epoxy and acrylate resin	Proprietary		12.000	mg	42811	18182
PCB				supplier	Immersion Gold	GOLD (Au)	7440-57-5		0.300	mg	1070	455
PCB				supplier	Electroless Nickel	Nickel (Ni)	7440-02-0		6.000	mg	21406	9091
Capacitor C201 (GRM0225COJ101JA02)	M-010 Ceramics / glass	0.090	mg	supplier	Copper alloys	Copper (Cu)	7440-50-8		0.027	mg	300000	41
Capacitor C201 (GRM0225COJ101JA02)				SVHC	Glass	Diboron trioxide; Boric oxide	1303-86-2		0.001	mg	6667	1
Capacitor C201 (GRM0225COJ101JA02)				supplier	Glass	Silicon dioxide	7631-86-9		0.002	mg	26667	4
Capacitor C201 (GRM0225COJ101JA02)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.003	mg	33333	5
Capacitor C201 (GRM0225COJ101JA02)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.002	mg	22222	3
Capacitor C201 (GRM0225COJ101JA02)				supplier	Tin plating	Tin (Sn)	7440-31-5		0.007	mg	77778	11



Capacitor C201 (GRM0225C0J101JA02)				supplier	Ceramic	Zirconium oxide	1314-23-4		0.024	mg	266667	36
Capacitor C201 (GRM0225C0J101JA02)				supplier	Ceramic	Calcium oxide	1305-78-8		0.019	mg	213333	29
Capacitor C201 (GRM0225C0J101JA02)				supplier	Ceramic	Misc	Proprietary		0.005	mg	53333	7
Capacitor C202 (GRM022R61A103KE19)	M-010 Ceramics / glass	0.090	mg	supplier	Copper alloys	Copper (Cu)	7440-50-8		0.026	mg	290000	40
Capacitor C202 (GRM022R61A103KE19)				SVHC	Glass	Diboron trioxide; Boric oxide	1303-86-2		0.001	mg	6444	1
Capacitor C202 (GRM022R61A103KE19)				supplier	Glass	Silicon dioxide	7631-86-9		0.002	mg	25778	4
Capacitor C202 (GRM022R61A103KE19)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.003	mg	33333	5
Capacitor C202 (GRM022R61A103KE19)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.002	mg	22222	3
Capacitor C202 (GRM022R61A103KE19)				supplier	Tin plating	Tin (Sn)	7440-31-5		0.007	mg	77778	11
Capacitor C202 (GRM022R61A103KE19)				supplier	Ceramic	Barium oxide, obtained by calcining witherite	1304-28-5		0.029	mg	326667	45
Capacitor C202 (GRM022R61A103KE19)				supplier	Ceramic	Titanium dioxide	13463-67-7		0.0147	mg	163333	22
Capacitor C202 (GRM022R61A103KE19)				supplier	Ceramic	Misc	Proprietary		0.0049	mg	54444	7
Capacitor C203 (GRM0225C1H100JA03)	M-010 Ceramics / glass	0.090	mg	supplier	Copper alloys	Copper (Cu)	7440-50-8		0.0270	mg	300000	41
Capacitor C203 (GRM0225C1H100JA03)				SVHC	Glass	Diboron trioxide; Boric oxide	1303-86-2		0.0006	mg	6667	1
Capacitor C203 (GRM0225C1H100JA03)				supplier	Glass	Silicon dioxide	7631-86-9		0.002	mg	26667	4
Capacitor C203 (GRM0225C1H100JA03)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.0030	mg	33333	5
Capacitor C203 (GRM0225C1H100JA03)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.002	mg	22222	3
Capacitor C203 (GRM0225C1H100JA03)				supplier	Tin plating	Tin (Sn)	7440-31-5		0.0070	mg	77778	11
Capacitor C203 (GRM0225C1H100JA03)				supplier	Ceramic	Zirconium oxide	1314-23-4		0.0240	mg	266667	36
Capacitor C203 (GRM0225C1H100JA03)				supplier	Ceramic	Calcium oxide	1305-78-8		0.019	mg	213333	29
Capacitor C203 (GRM0225C1H100JA03)				supplier	Ceramic	Misc	Proprietary		0.005	mg	53333	7
Capacitor C206 (GRM033R60J474ME90)	M-011 Other inorganic materials	0.330	mg	supplier	Copper alloys	Copper (Cu)	7440-50-8		0.068	mg	207273	104
Capacitor C206 (GRM033R60J474ME90)				SVHC	Glass	Diboron trioxide; Boric oxide	1303-86-2		0.002	mg	4606	2
Capacitor C206 (GRM033R60J474ME90)				supplier	Glass	Silicon dioxide	7631-86-9		0.006	mg	18424	9
Capacitor C206 (GRM033R60J474ME90)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.007	mg	21212	11
Capacitor C206 (GRM033R60J474ME90)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.008	mg	24242	12
Capacitor C206 (GRM033R60J474ME90)				supplier	Tin plating	Tin (Sn)	7440-31-5		0.019	mg	57576	29
Capacitor C206 (GRM033R60J474ME90)				supplier	Ceramic	Barium oxide, obtained by calcining witherite	1304-28-5		0.132	mg	400000	200
Capacitor C206 (GRM033R60J474ME90)				supplier	Ceramic	Titanium dioxide	13463-67-7		0.066	mg	200000	100
Capacitor C206 (GRM033R60J474ME90)				supplier	Ceramic	Misc	Proprietary		0.022	mg	66667	33
Capacitor C207 (GRM033R60J224ME15)	M-011 Other inorganic materials	0.330	mg	supplier	Copper alloys	Copper (Cu)	7440-50-8		0.068	mg	207273	104
Capacitor C207 (GRM033R60J224ME15)				SVHC	Glass	Diboron trioxide; Boric oxide	1303-86-2		0.002	mg	4606	2
Capacitor C207 (GRM033R60J224ME15)				supplier	Glass	Silicon dioxide	7631-86-9		0.006	mg	18424	9
Capacitor C207 (GRM033R60J224ME15)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.007	mg	21212	11
Capacitor C207 (GRM033R60J224ME15)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.008	mg	24242	12
Capacitor C207 (GRM033R60J224ME15)				supplier	Tin plating	Tin (Sn)	7440-31-5		0.019	mg	57576	29
Capacitor C207 (GRM033R60J224ME15)				supplier	Ceramic	Barium oxide, obtained by calcining witherite	1304-28-5		0.132	mg	400000	200
Capacitor C207 (GRM033R60J224ME15)				supplier	Ceramic	Titanium dioxide	13463-67-7		0.066	mg	200000	100
Capacitor C207 (GRM033R60J224ME15)				supplier	Ceramic	Misc	Proprietary		0.022	mg	66667	33
Capacitor C209,C212 (GRM022R60J103M)	M-011 Other inorganic materials	0.180	mg	supplier	Copper alloys	Copper (Cu)	7440-50-8		0.052	mg	290000	79
Capacitor C209,C212 (GRM022R60J103ME19)				SVHC	Glass	Diboron trioxide; Boric oxide	1303-86-2		0.0012	mg	6444	2
Capacitor C209,C212 (GRM022R60J103ME19)				supplier	Glass	Silicon dioxide	7631-86-9		0.005	mg	25778	7
Capacitor C209,C212 (GRM022R60J103ME19)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.006	mg	33333	9
Capacitor C209,C212 (GRM022R60J103ME19)				supplier	Nickel and Nickel alloys	Nickel (Ni)	7440-02-0		0.004	mg	22222	6
Capacitor C209,C212 (GRM022R60J103ME19)				supplier	Tin plating	Tin (Sn)	7440-31-5		0.014	mg	77778	21
Capacitor C209,C212 (GRM022R60J103ME19)				supplier	Ceramic	Barium oxide, obtained by calcining witherite	1304-28-5		0.059	mg	326667	89
Capacitor C209,C212 (GRM022R60J103ME19)				supplier	Ceramic	Titanium dioxide	13463-67-7		0.029	mg	163333	45
Capacitor C209,C212 (GRM022R60J103ME19)				supplier	Ceramic	Misc	Proprietary		0.010	mg	54444	15
Capacitor C213 (GRM022R60J473ME15)	M-011 Other inorganic materials	0.090	mg	supplier	Copper alloys	Copper (Cu)	7440-50-8		0.026	mg	290000	40
Capacitor C213 (GRM022R60J473ME15)				SVHC	Glass	Diboron trioxide; Boric oxide	1303-86-2		0.001	mg	6444	1